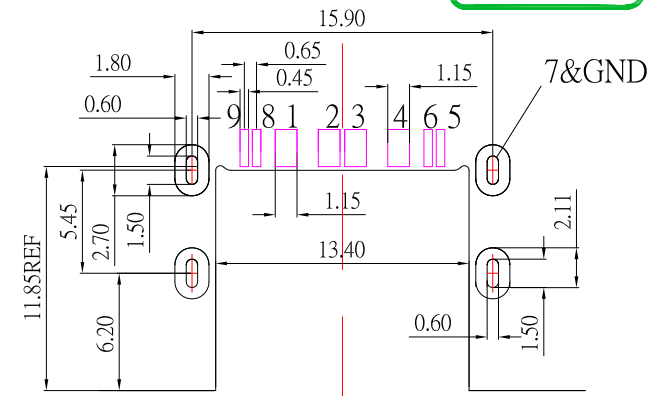




SUA-110E16-32x-S242

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Phosphor Bronze

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Rate: 3.0 A

3.2 insulator Resistance:1000MΩ Min

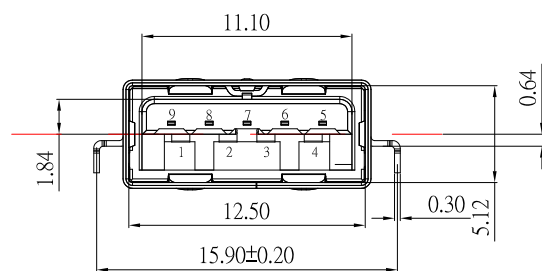
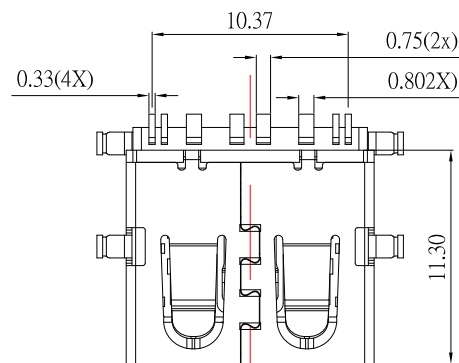
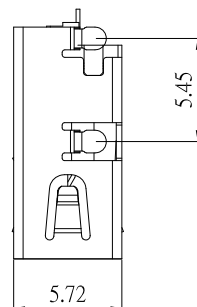
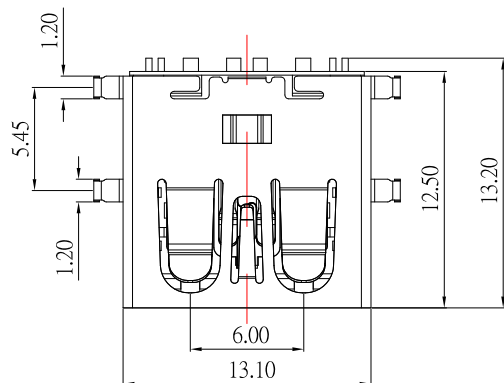
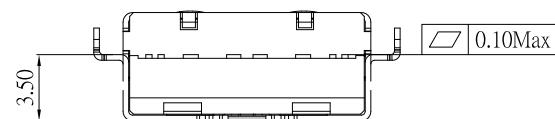
3.3 Dielectric Strength: 500V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -25°C ~ +85°C

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



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TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao
DATE: 05/13/21
DATE: 05/13/21
DATE: 05/13/21

MATL	TITLE	CONNECTOR
FINISH	MODLE	USB AF 3.0 沉板 板上H3.50mm 無捲邊 GEN 2
SCALE	DWG NO.	SUA-110E16-32x-S242
SHEET NO.	PART NO.	SUA-110E16-32x-S242

SIZE
A4
VER
R